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Call for Papers

SEMICON® Europa2008

Advanced Packaging Conference

Wednesday 8 & Thursday 9 October Stuttgart Germany In conjunction with SEMICON Europa 2008

Semiconductor Equipment and Materials International (SEMI) and the European Chapter of International Microelectronics and Packaging Society (IMAPS), invite packaging professionals to submit proposals for the Advanced Packaging Conference, which will be held on Wednesday 8 and Thursday 9 October in conjunction with SEMICON Europa 7-9 October 2008 in Stuttgart, Germany. This technical conference will focus on solutions in advanced device packaging manufacturing operations.

Presentations on original, non-commercial works describing recent developments are being solicited under the theme of ***"Embedded Die Technologies".***

NEW TECHNOLOGIES, CHALLENGES AND OPPORTUNITIES

- Wafer Level Packaging, Chip Scale Packaging, Bumping, Ball Grid Technologies
- Wafer Level Integration
- System in Package (SiP), Package on Package, Heterogeneous 3D Packaging
- Market/ Application drivers, Roadmaps, Supply chain
- Chip / Package Co-Design, Concurrent engineering

ADVANCED MANUFACTURING TECHNOLOGIES

- New Processes, Tools and Materials
- New approaches in testing (Reliability, Validation, Test and Failure Analysis Techniques)
- Cost Management, Cost of Ownership, Supplier-Customer improvement programs.
- Carriers and Substrates, Silicon Interposer

Furthermore, R&D Institutes, Universities and Start-ups are encouraged to propose innovative equipment, materials and technology presentations.

Instructions to submit a paper proposal - Submit the following information in an e-mail

- Specify which of the above subject areas your presentation falls in to
- Presentation title
- Abstract of 200-400 words (descriptive paragraph identifying issue addressed and solution)
- Short biography of the author
- Author contact details (Job title, company, address, telephone and e-mail)
- Contact person details i.e. Personal Assistant (Job title, company, address, telephone and e-mail)
- Indicate in subject box of e-mail: ADV. PACK. Call for papers

Please submit ALL the above information in one e-mail by 5 May 2008 to europrograms@semi.org
Your presentation will not be included in the review process unless the information is complete.

Evaluation criteria include significance, usefulness for the manufacturing world and clarity and accuracy as a paper. Abstracts will be peer-reviewed. We encourage application related presentations, i.e. on joint projects between users and suppliers. Papers are to be non-commercial and focus on the technical/economical merits of a process rather than the individual company's product benefits.

Selected presenters will be notified by 6 June 2008.

Program Committee: Andy Longford, (Committee Chairman), PandA Europe; Andreas Fischer, Bosch; Christian Ossmann Datacon Technology; Philip Homami, F&K Delvotec; Ignas van Dommelen, Elmos; Rolf Aschenbrenner, Fraunhofer IZM; Eric Beyne, IMEC; Jens Mueller, IMAPS; Klaus Pressel, Infineon Technologies; Eef Bagerman, NXP Semiconductors; Andreas Dill, Oerlikon; Elke Zakel, PacTech; Carlo Cognetti, STMicroelectronics; Dietrich Toennies, Suss MicroTec

For more information, please visit www.semi.org/semiconeuropa or contact SEMI Europe +32.2.289.64.99

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